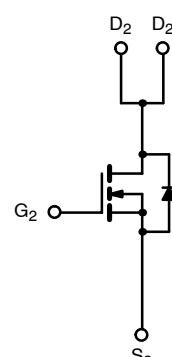
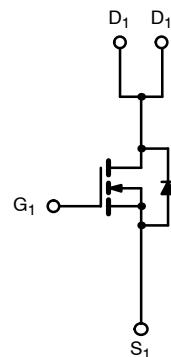
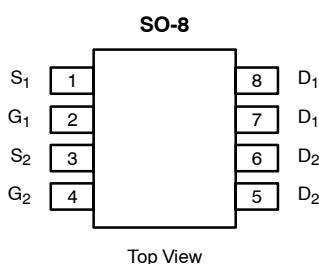


Dual N-Channel 30-V (D-S) MOSFET

TrenchFET®
Power MOSFETs

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
30	0.022 @ $V_{GS} = 10$ V	7.5
	0.030 @ $V_{GS} = 4.5$ V	6.5



Ordering Information: Si4804DY
Si4804DY-T1 (with Tape and Reel)

N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	10 secs	Steady State	Unit
Drain-Source Voltage	V_{DS}	30		
Gate-Source Voltage	V_{GS}	± 20		V
Continuous Drain Current (T _J = 150°C) ^a	T _A = 25°C	I _D	7.5	A
	T _A = 70°C		6.0	
Pulsed Drain Current	I _{DM}	20		
Continuous Source Current (Diode Conduction) ^a	I _S	1.7	0.9	A
Maximum Power Dissipation ^a	T _A = 25°C	P _D	2.0	W
	T _A = 70°C		1.3	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150		°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R _{thJA}	52	°C/W
	Steady State		93	
Maximum Junction-to-Foot (Drain)	R _{thJF}	35	40	

Notes

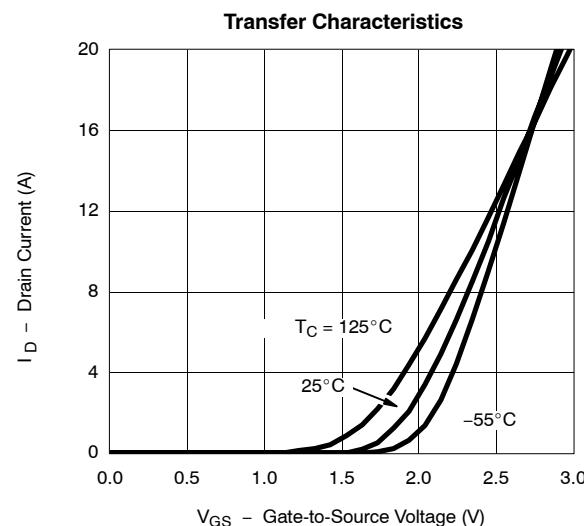
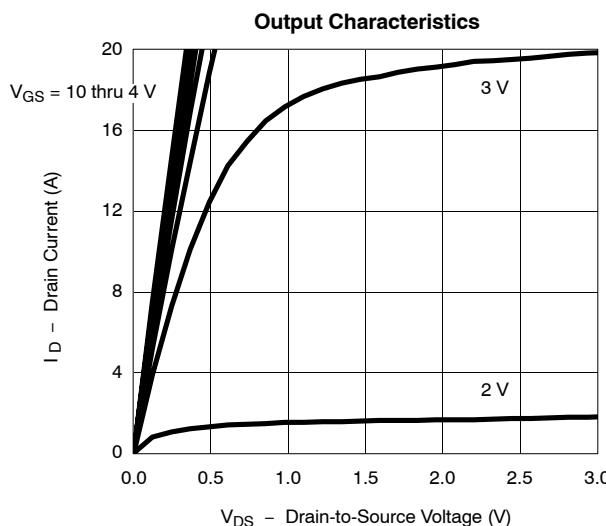
a. Surface Mounted on 1" x 1" FR4 Board.

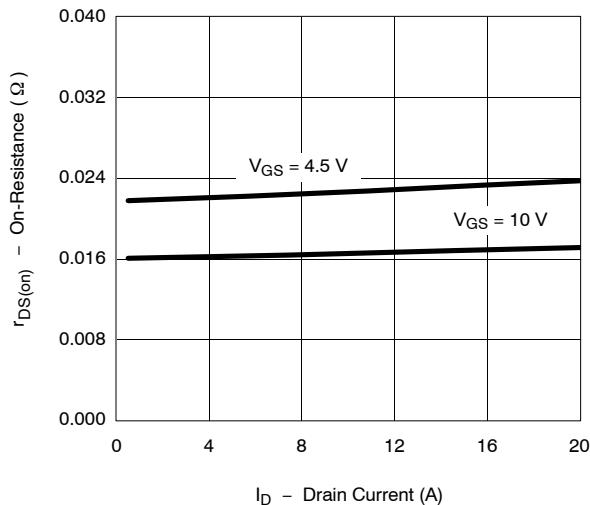
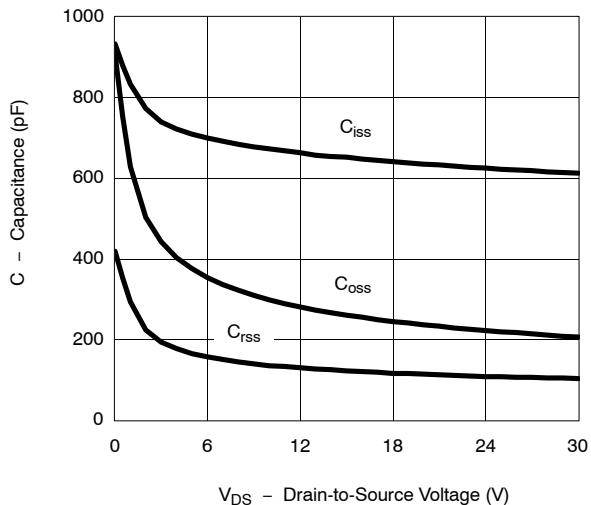
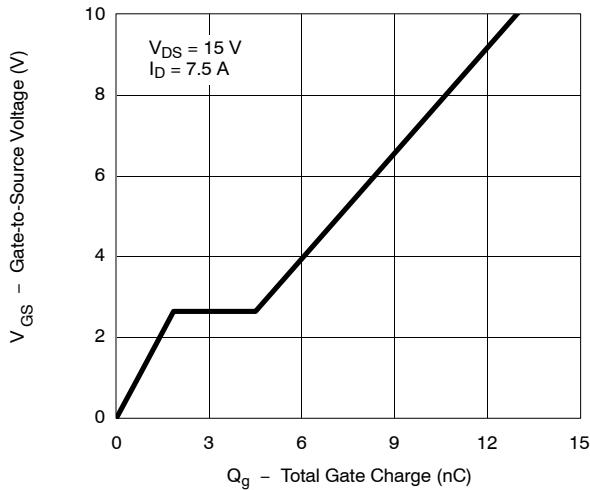
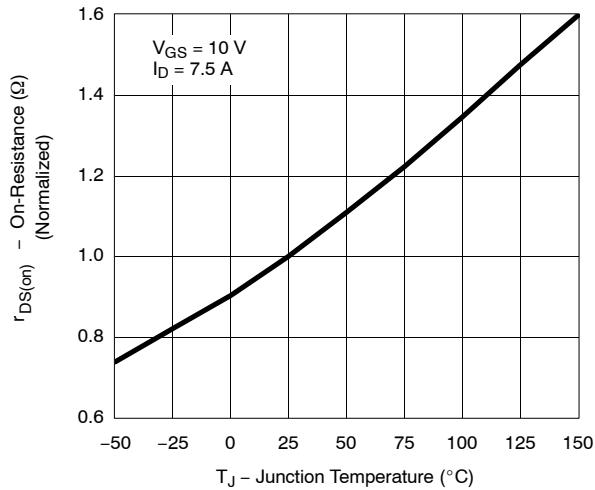
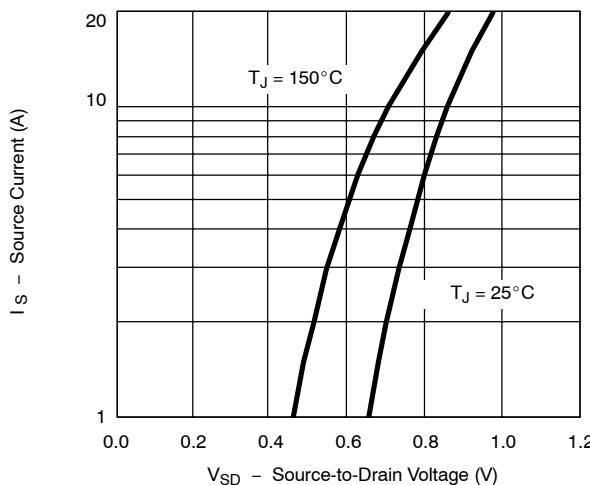
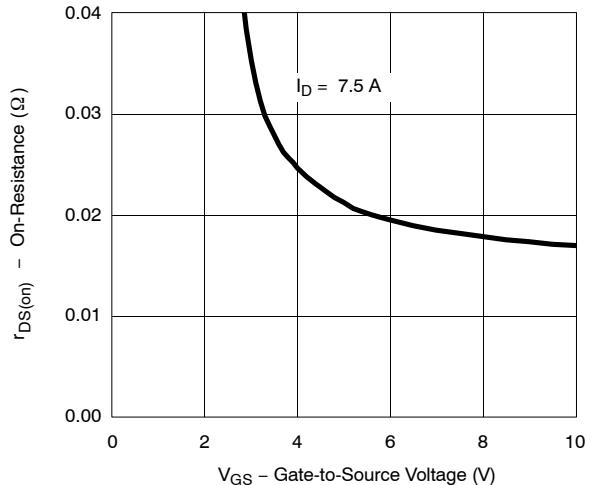
SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.8			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$		1		μA
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$		5		
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		0.018	0.022	Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$		0.024	0.030	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 7.5 \text{ A}$	22			S
Diode Forward Voltage ^a	V_{SD}	$I_S = 1.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		13	20	nC
Gate-Source Charge	Q_{gs}			2		
Gate-Drain Charge	Q_{gd}			2.7		
Gate Resistance	R_G		0.5	1.9	4	Ω
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$ $I_D \approx 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$		8	16	ns
Rise Time	t_r			10	20	
Turn-Off Delay Time	$t_{d(\text{off})}$			21	40	
Fall Time	t_f			10	20	
Source-Drain Reverse Recovery Time	t_{rr}		$I_F = 1.7 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	40	80	

Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

